

ORGANIZING INFORMATION

THE CONFERENCE IS HELD AT:

Střední škola informatiky
Čichnova 23, 624 00 BRNO-Komín

How to get there: see incl. plan by a car

From the Brno Trade Fair Exhibition Centre go in direction Brno-dam. After approx. 4 km you will see the OPEL car shop centre, on the left side. At the crossroads in front of the OPEL go to the left, at the next crossroads to the right and on the right side you will see an educational centre:

Střední škola informatiky
street Čichnova 23, BRNO-Komín

BINDING APPLICATIONS:

Will be mailed together with obligatory demand for accommodation and meals before **October 12, 2018** to the address:

SMT-INFO consortium
Údolní 53, 602 00 Brno
CZECH REPUBLIC
e-mail: smtinfo@nexta.cz, smtinfocz@gmail.com
mobile: 00420-602 542 966

Accommodation with meals:

Participants will be accommodated in the BOBY CENTRUM Brno ***

Registration:

In the conference hall
October 16, 2018 8.30–9.00 a.m.

PROFESSIONAL GUARANTOR:

SMT-INFO, Údolní 53, 602 00 Brno
CZECH REPUBLIC

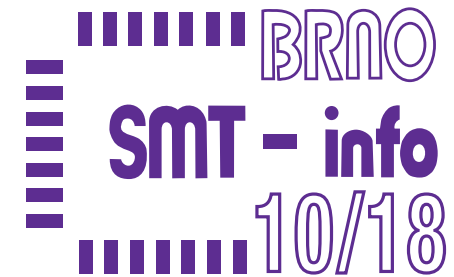
tel.: 00420-541 146 113
mobil: 00420-602 542 966
e-mail: smtinfo@nexta.cz, smtinfocz@gmail.com
Internet: www.smtinfo.cz

SMT-INFO CONSORTIUM

in cooperation with

FEKT VUT Brno
and
SŠ INFORMATIKY BRNO

have the pleasure to invite you
for the twenty-seventh cycle
new techniques & technologies presentation
in the international conference



**SOLDERING AND CLEANING
PCB's IN ELECTRONICS**

**NEW TRENDS
IN MICROELECTRONICS**

SOLDER JOINT DEFECTS

BRNO, October 16, 2018
SŠ informatiky
Čichnova 23, Brno-Komín

event. code 10/18

SMT-INFO consortium
Údolní 53
602 00 BRNO
Czech Republic

CONFERENCE ORIENTATION:

- SOLDERING AND CLEANING IN ELECTRONICS
- NEW TRENDS IN MICROELECTRONICS
- TECHNIQUES IN REPAIRING
- SOLDER JOINT DEFECTS

PROFESSIONAL OFFER

- Conference participants will be acquainted with the latest information on above mentioned topics presented by specialist from prestigious companies.
- In a room adjacent the lecture theatre, the following company stands will be installed and professional literature and demonstration equipment will be offered there:

ADOPT SMT MAROX
AIM SOLDER EUROPE PAN ELECTRONIC
AMTEST - GROUP SMT SERVICE + INERTEC

**Media Partner of the Conference is the Magazine
 PCB ELECTRONICS A-Z**

- Advertisement tables will be available for the conference participants and visitors, providing propagation of their own products and offer of non-used/used technological equipment and services.

**THEMATIC ORIENTATION OF OTHER EVENTS
 ORGANIZED BY SMT-INFO:**

SMT-INFO 02/19 Brno, 19th February, 2019
 Technical and Business Seminar

- PCB DESIGN SYSTEMS
- PCB PRODUCTION AND DEFECTS
- COMPLEX PRODUCTION LINES FOR MODERN ASSEMBLY
- INSPECTION SYSTEMS

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CONFERENCE SCHEDULE

Tuesday, October 16, 2018

- 9.00 - Opening, Introduction
- 9.10 - Offer of SMT Expert Activities from Department of Electrotechnology Czech Technical University in Prague /K. Dušek, ČVUT FEL Praha/
- 9.30 - A Practical Guide to Optimizing Solder Paste Performance for Ultra Fine Feature Printing /A. Sedlák, AIM SOLDER EUROPE Lodz/
- 9.50 - Latest in AMTEST portfolio
 - BLUIRIS First Article Inspection
 - PCB Separation – ELITE automatic /I. Kalászi, AMTEST-GROUP, J. Vondráček, AMTEST-GROUP Brno/
- 10.20 - Refreshment, Coffee
- 10.40 - Selective Soldering INERTEC /J. Elbert, INERTEC, M. Galajda, SMT SERVICE Košice/
- 11.00 - ATF Soldering Machines for Vapour Phase Soldering /M Berberich, ATF, M. Abel, ABETEC Pardubice/
- 11.20 - Latest in Soldering Technologies from ERSA /M. Duda, PBT Rožnov pod Radhoštěm/
- 11.40 - Discussion
- 11.50 - Practical Experiences of Vapour Phase Soldering /K. Malysz, MP ELEKTRONIK TECHNOLOGIE Blansko/
- 12.10 - Selective Soldering from Nordson SELECT /L. Pokorný, AMTEST-GROUP Brno/
- 12.30 - Methods for Qualification of Cleaned Electronic Assemblies and Validation of Cleaning Process Changes. Common Ways for Ensuring and Proving Assemblies against Electrochemical Corrosion. /V. Sítko, PBT WORKS Rožnov pod Radhoštěm/
- 13.10 - Lunch
- 13.50 - Low Temperature Solder Paste ALPHA M-550 /C. Hoppenbrouers, ALPHA, M.Cichra, ERMEG Liberec/
- 14.50 - Electrostatics – Problems and Hazards (IEC 61340, ATEX 2014/34/EU, Wikipedia) /K.Jurák, Praha , Z.Nejezchlebová, Agentura ČAS Praha/
- 15.10 - Discussion, Conference Closing

**Lectures in English and German will be interpreted.
 Program changes reserved.**

Obligatory application for international conference

**SOLDERING AND CLEANING PCB's
 IN ELECTRONICS**

NEW TRENDS IN MICROELECTRONICS

SOLDER JOINT DEFECTS

October 16, 2018

Name and surname, title

Factory name and address (ZIP code)

Job function

Telephone Telefax

e-mail

Lunch

October 16, 2018

yes-no

.....
Participant signature

.....
Stamp and signature
of the organization